

Material Composition Specification

GPR-4AM Case



Device average mass 947 mg
 Fluctuation margin +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.26%	2.48	Si	7440-21-3	0.26%	2.48	2,619
axial lead	wire	79.56%	753.39	Cu	7440-50-8	79.51%	752.94	795,079
				Zn	7440-66-6	0.05%	0.45	475
	moly slug	14.21%	134.6	Mo	7439-98-7	14.21%	134.6	142,133
die attach	solder	0.57%	5.38	Cu	7440-50-8	0.45%	4.3	4,541
				Ag	7440-22-4	0.09%	0.81	855
				P	7723-14-0	0.03%	0.27	285
encapsulation	glass	4.01%	38	Zn	7440-66-6	1.93%	18.24	19,260
				O	7782-44-7	1.47%	13.95	14,730
				B	7440-42-8	0.38%	3.6	3,801
				Si	7440-21-3	0.15%	1.45	1,531
				Pb	7439-92-1	0.08%	0.76	803
plating*	tin/lead process	1.39%	13.17	Sn	7440-31-5	1.18%	11.2	11,827
				Pb	7439-92-1	0.21%	1.97	2,080
	matte tin	1.39%	13.17	Sn	7440-31-5	1.39%	13.17	13,907

*For Lead Free plating, add suffix "PB FREE" to part number.
 For Tin/Lead plating, add suffix "TIN/LEAD" to part number.
 No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R5 (16-July 2018)